NXP Semiconductors Hong Kong Ltd

NXP Semiconductors N.V. (Nasdaq: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications. Headquartered in Europe, the company has approximately 28,000 employees working in more than 25 countries and posted sales of USD 3.8 billion in 2009.

The Industrial Technology and Engineering Center (ITEC) is an OEM department of NXP which develops, manufactures, sells and services leading edge equipment for assembly and testing of (discrete) semiconductors. The ITEC products are Die bonders, Wire Bonders, Testers (electrical final test) and Tapers / Die sorters.

The ITEC organization in Hong Kong consists of:
- Product teams with focus on product improvement, application development and customer support
- An Operations group, for logistical support, supply chain management, service coordination and supply of mature equipment and parts

To cope with the business needs, we are seeking experienced candidates for the following position:

**Chief Equipment Software Design Engineer**

**Responsibilities**

- Responsible for software improvements and building blocks required for wire bond equipment of the installed base
- Work closely with the customer by getting defined demands and study the feasibility in cooperation with the R&D Nijmegen architect
- Verify the feasibility of the conceptual objectives and estimate the time required and the cost involved
- Conduct studies / simulations to verify ideas and adjust the global design
- Implement the software on the equipment and release it according to the aligned plan

**Requirements**

- University graduate in MSc/ BSc in Software Engineering, Computer Science or Physics
- At least 7 years relevant working experience in embedded software design
- High performance system design in semiconductor packaging or related assembly processes
  - Embedded Software, possesses most of the following technical skills:
- Object Oriented programming techniques
- Embedded software (ADA)
- Very High Definition Language (VHDL)
- Machine vision
- System control
- Good interpersonal skills and able to deliver results through determination and team-work
- Self-motivated and be innovative
- Strong problem-solving and analytical skills (six sigma, 8D or Shainin methods)
- Good leadership skills and able to lead virtual teams, and has excellent inter-personal skills
- Able to work independently and under pressure
- Excellent command of written and spoken in English, Cantonese and Mandarin

We offer competitive remuneration package, fringe benefits and prospects for suitable candidate. Please e-mail full resume with expected salary to hr-recruit.edl@nxp.com. We regret that only shortlisted candidates will be notified.

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We are an equal opportunity employer. All information provided by applicants will be treated in strict confidence and used only for recruitment purposes and all data will be destroyed within 12 months.